



11th International Conference on
**High Temperature
Ceramic Matrix Composites**

Aug 27 – 31, 2023

Ramada Plaza Jeju Hotel, Jeju, Korea

**Sponsorship &
Exhibition Prospectus**

Hosted by



Supported by



WELCOME ADDRESS

Welcome to the HT-CMC 11 in Jeju, Korea

Dear Colleagues,

It is with much pride that we invite all experts from all over the world to the HT-CMC 11 in Jeju, Korea from August 27 to 31, 2023. The Korean Ceramic Society will have the privilege of hosting this meaningful conference.

The conference will provide a variety of programs including distinguished presentations, exhibition, networking events. Further, there would be enriching discussions and initiative collaborations within and across disciplines for the advancement of your research. Your active participation will be essential for the great success of the conference.

Furthermore, our sponsorship prospectus has been designed to offer you wide range of options to raise the visibility of your business and to deliver your key message to attendees. You will be given unparalleled opportunities to expose your brand and have a visible presence in front of an important audience.

For the sponsors of HT-CMC 11, the Committee will make its best effort to deliver your latest company information, corporate policy, program and products in a more diverse and efficient way to participants home and abroad. It would be appreciated if you recognize the importance and value of the conference and provide sponsorship and cooperation for the successful hosting of HT-CMC 11.

Conference Chairs



Ji Yeon PARK

*Korea Atomic Energy Research Institute,
Korea*



Laifei CHENG

*Northwestern Polytechnical University,
China*



Hai-Doo KIM

Soonchunhyang University, Korea

Local Organizing Committee



Kee Sung LEE

Kookmin University



Se Young KIM

Korea Institute of Energy Research



Weon-Ju KIM

Korea Atomic Energy Research Institute



Yoon-Suk OH

*Korea Institute of Ceramic Engineering and
Technology*



Yoonjoo LEE

*Korea Institute of Ceramic Engineering and
Technology*



HT-CMC 11 will continue the successful previous conferences firstly held in Bordeaux, France (1993). This conference series has been recognized as the global and central meeting event in high-temperature ceramic composite science and technology.

Energy efficient and ecofriendly technologies and systems are critically needed for further growth and sustainable development.

While ceramic matrix composites were originally developed to overcome problems associated with the brittle nature of monolithic ceramics, today the composites can be tailored for customized purposes and offer energy efficient and ecofriendly applications, including aerospace, ground transportation, and power generation systems.

Title	11th International Conference on High Temperature Ceramic Matrix Composites (HT-CMC 11)		
Date	August 27 (Sun) – 31 (Thu), 2023		
Venue	Ramada Plaza Jeju Hotel, Jeju, Korea		
Organized by	The Korean Ceramic Society		
Scale	400 Attendees from 20 Countries Expected		
Programs	Plenary & Invited & Oral & Poster Session, Welcoming Cocktail, Banquet		
Website	www.ht-cmc11.org		
Key Dates	Abstract Submission	February 28, 2023	
	Abstract Acceptance	March 31, 2023	
	Early Registration	April 30, 2023	
HT-CMC History	HT-CMC 10	2019 Bordeaux, France	
	HT-CMC 9	2016 Toronto, Canada	
	HT-CMC 8	2013 Xi'an, China	
	HT-CMC 7	2010 Bayreuth, Germany	
	HT-CMC 6	2007 New Delhi, India	
	HT-CMC 5	2004 Seattle, USA	
	HT-CMC 4	2001 Munich, Germany	
	HT-CMC 3	1998 Osaka, Japan	
	HT-CMC 2	1995 Santa Barbara, USA	
	HT-CMC 1	1993 Bordeaux, France	
Secretariat	The Korean Ceramic Society Meorijae Building, Suite #403, 76, Bangbae-ro, Seocho-gu, Seoul 06704, Republic of Korea Tel: +82-2-565-3571 E-mail: secretary@ht-cmc11.org		

Program

	Aug 27 (Sun)	Aug 28 (Mon)	Aug 29 (Tue)	Aug 30 (Wed)	Aug 31 (Thu)
AM		Opening Ceremony & Plenary Session	Plenary Session Technical Sessions	Plenary Session Technical Sessions	Plenary Session Technical Sessions
	Lunch				
PM	Registration	Technical Sessions	Technical Sessions	Technical Sessions Excursion	Technical Sessions Closing Ceremony
	Welcoming Cocktail 			Banquet 	



The renowned experts lecture which will contribute to the process of understanding the latest trend in high temperature ceramic matrix composites and establishing further strategy of proceeding to new technology and generating new industry

The space of communication and cooperation between organizations, firms and world experts in the field / Establishing the leading and global impression in the field

The opportunity to present the research on the latest issue and applied technology in high temperature ceramic matrix composites and related technology

The ground of research presentation and network of world experts

Symposia

Sym 01 Computational Modeling and Design of New Materials and Processes

Sym 02 Fibers, Preforms and Interphases

Sym 03 Polymer Derived Ceramics and Composites

Sym 04 Innovative Design, Advanced Processing, and Manufacturing Technologies in Non-oxide and Oxide Composites

Sym 05 Advanced Thermal and Environmental Barrier Coatings: Processing, Properties, and Applications

Sym 06 Carbon/Carbon Composites

Sym 07 Materials for Extreme Environments: UHTCs and MAX phases

Sym 08 Additive Manufacturing of Ceramics and Composites

Sym 09 Nanocomposites: Carbon Nanotube, Graphene, Particulate, etc

Sym 10 Testing and Evaluation of Composites (Thermomechanical Behavior and Performance of Composites / Standard and DB)

Sym 11 Joining and Integration Technologies

Sym 12 CMC Applications I (Aerospace, Ground Transportation)

Sym 13 CMC Applications II (Power Generation Systems)

Committee

Conference Chairs

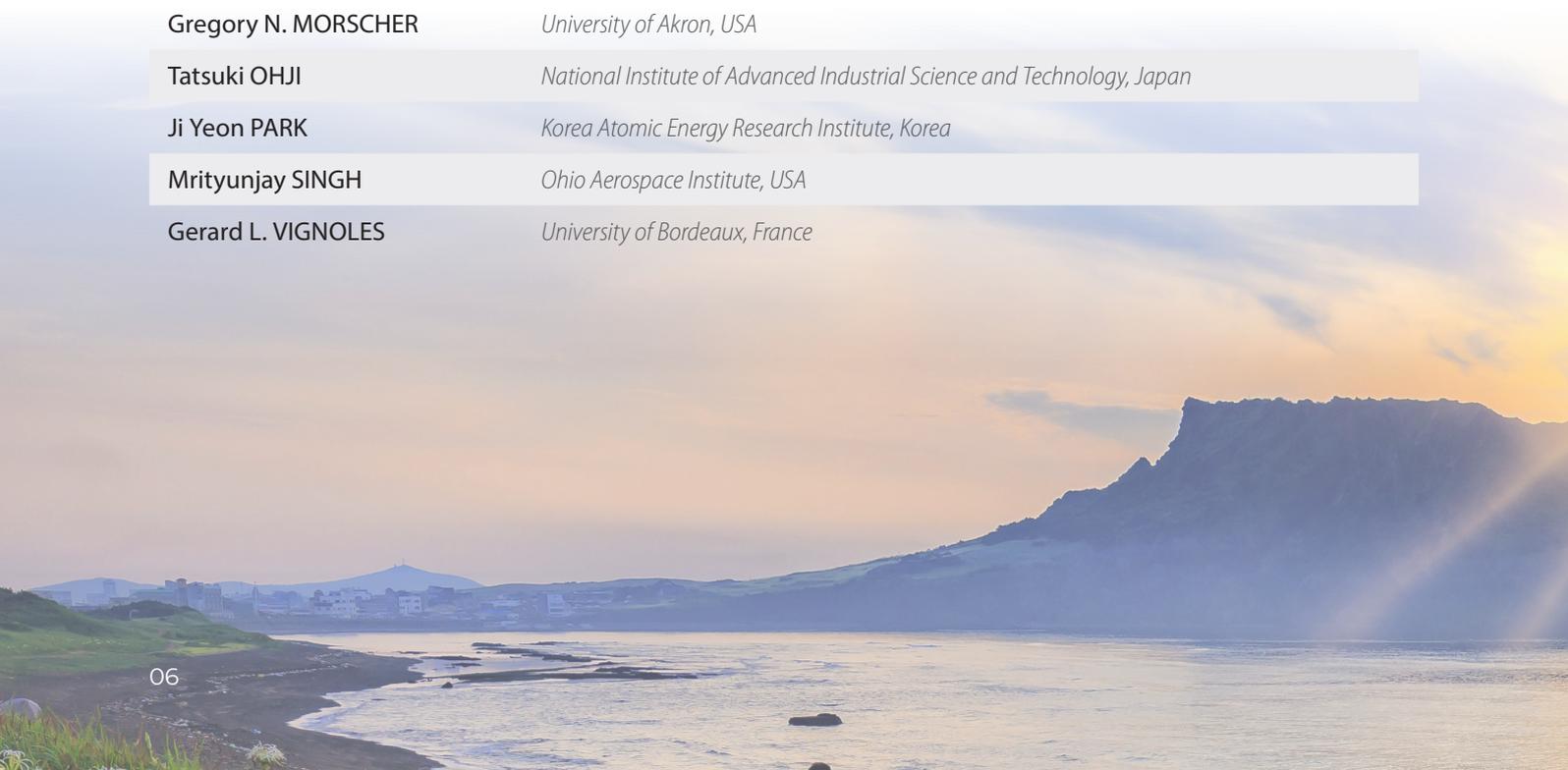
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Laifei CHENG	<i>Northwestern Polytechnical University, China</i>

Honorary Chair

Hai-Doo KIM	<i>Soonchunhyang University, Korea</i>
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Local Organizing Committee

Chair

Kee Sung LEE *Kookmin University, Korea*

Secretary

Se Young KIM *Korea Institute of Energy Research, Korea*

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Weon-Ju KIM *Korea Atomic Energy Research Institute, Korea*

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Dong-Ho RHEE *Korea Aerospace Research Institute, Korea*

Sponsorship Program

Financial Backing

DIAMOND

USD 10,000

Free Registration 5

Pre-Marketing

- E-banner on Website Main Page
- Logo on E-newsletter & Website

On-site Marketing

- Program Book –Advertisement 1P: First Priority
- Projection of Logo in the Session Room during Intermission
- Logo on Banner
- Insertion of Company Leaflet in Conference Kit

PLATINUM

USD 7,000

Free Registration 4

Pre-Marketing

- E-banner on Website Main Page
- Logo on E-newsletter & Website

On-site Marketing

- Program Book –Advertisement 1P: Second Priority
- Projection of Logo in the Session Room during Intermission
- Logo on Banner
- Insertion of Company Leaflet in Conference Kit

GOLD

USD 5,000

Free Registration 3

Pre-Marketing

- E-banner on Website Main Page
- Logo on E-newsletter

On-site Marketing

- Program Book –Advertisement 1P: Third Priority
- Projection of Logo in the Session Room during Intermission
- Logo on Banner
- Insertion of Company Leaflet in Conference Kit

SILVER

USD 3,000

Free Registration 2

Pre-Marketing

- Logo on E-newsletter

On-site Marketing

- Program Book –Advertisement 1P: Forth Priority
- Insertion of Company Leaflet in Conference Kit

BRONZE

USD 2,000

Free Registration 1

Pre-Marketing

- Logo on E-newsletter

On-site Marketing

- Program Book –Advertisement 1P: Fifth Priority
- Insertion of Company Leaflet in Conference Kit

In-kind Support

BANQUET | USD 20,000



- Free Registration: 5
- CEO's Congratulatory Speech and Company's Advertising Film at the Banquet
- Logo on Banner
- E-banner on Website Main Page
- Logo on E-newsletter & Website
- Projection of Logo in the Session Room during Intermission

NAME BADGE LANYARD | USD 10,000



- Free Registration: 2
- Logo Marked on Name Badge Lanyard
- Logo on Banner
- E-banner on Website Main Page
- Logo on E-newsletter & Website
- Projection of Logo in the Session Room during Intermission

COFFEE BREAK | USD 5,000



- Logo on Paper Cup of Coffee Break
- E-banner on Website Main Page
- Projection of Logo in the Session Room during Intermission
- Logo on Banner
- Logo on E-newsletter & Website

PEN/NOTEPAD | USD 3,000



- Logo on Pen or Notepad (Souvenir)
- Logo on E-newsletter & Website

ADVERTISEMENT | USD 1,000



- Program Book: Advertisement 1P



Sponsorship Application Form

A. Company Information

Name of Company			
Address			
Country		Name of President	
Person in Charge		Division in Charge	
Tel		Website	
E-mail			

B. Sponsorship Program

	Category	Sponsor Amount
Financial Backing	<input type="checkbox"/> Diamond Sponsor	USD 10,000
	<input type="checkbox"/> Platinum Sponsor	USD 7,000
	<input type="checkbox"/> Gold Sponsor	USD 5,000
	<input type="checkbox"/> Silver Sponsor	USD 3,000
	<input type="checkbox"/> Bronze Sponsor	USD 2,000
In-kind Support	<input type="checkbox"/> Banquet	USD 20,000
	<input type="checkbox"/> Name Badge Lanyard	USD 10,000
	<input type="checkbox"/> Coffee Break	USD 5,000
	<input type="checkbox"/> Pen / Notepad	USD 3,000
	<input type="checkbox"/> Advertisement	USD 1,000

C. Application & Payment

• Application Deadline: **July 21, 2023**

• Wire transfer only. Credit card payment will not be accepted. All transaction fees are borne by the applicant.

• Account Holder: The Korean Ceramic Society

• Bank: Woori Bank

• Swift Code: HVBKRRSE

• Account Number: 1005-302-383204

• Address of Bank: 76, Bangbae-ro, Seocho-gu, Seoul, Republic of Korea

• Address of Account Holder: Meorijae Building, Suite #403, 76, Bangbae-ro, Seocho-gu, Seoul 06704, Republic of Korea

By signing this form, I apply for the sponsorship of HT-CMC 11 and agree to the HT-CMC 11 Sponsorship terms and conditions.

Company Authorized Signature : _____

Date : _____

Secretariat of HT-CMC 11

Contact Person: Ms. Minjung Kim

E-mail: secretary@ht-cmc11.org

Tel: +82-2-565-3571

Website: www.ht-cmc11.org

Exhibition Information

Key Reasons to Exhibit

One of the trendy and professional exhibitions in the field

Begun as a global networking and technological exchange, the HT-CMC conference is recognized as the premier event of its field for all high temperature ceramic matrix composites and related issues.

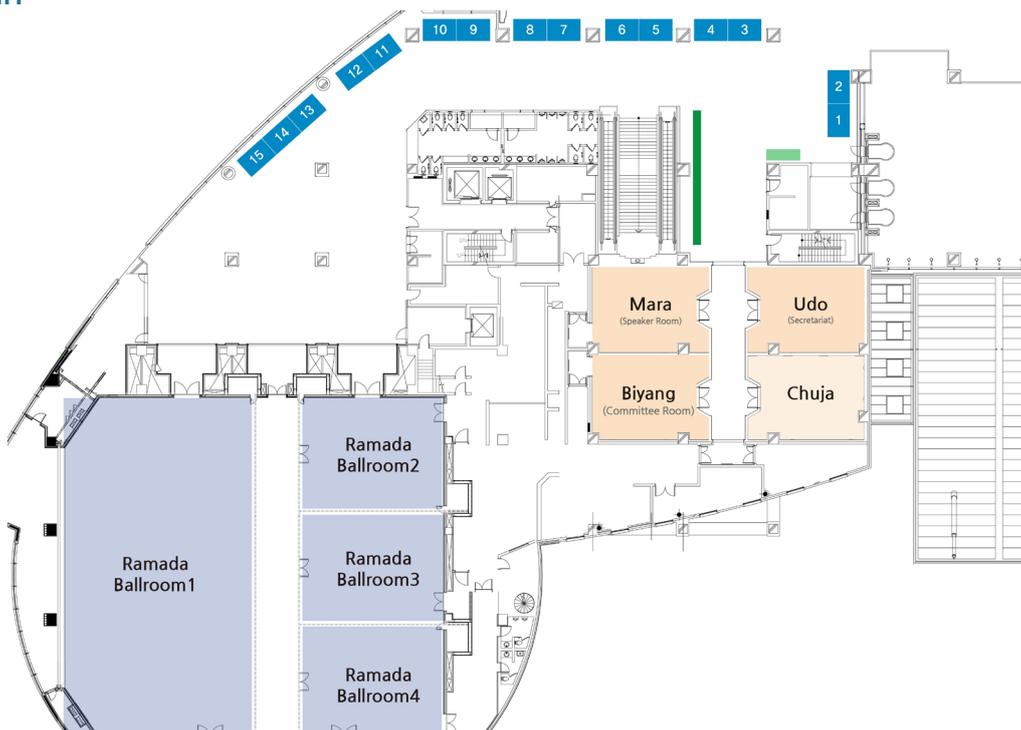
Excellent platform to extend your marketing reach worldwide

Enables the raising of your product and brand awareness and builds name recognition worldwide through direct marketing to targeted groups of approximately 500 participants from all around the world.

Overview

Exhibition Schedule	<ul style="list-style-type: none"> • Exhibitor Move-in: August 27 (Sun), 2023 • Exhibition: August 28 (Mon) - 30 (Wed), 2023 • Removal: August 31 (Thu), 2023
Venue	Ramada Plaza Jeju Hotel
1 Standard Booth	3m (width) × 2m (depth) × 2.5m (height)
Participation Fee	USD 3,000 / KRW 3,000,000
Participation Fee Includes	<ul style="list-style-type: none"> • Costs and Charges for Exhibition Space, Standard Booth Package • Directory Entry / Exhibitor Passes • 2 Free Registrations per Booth (2 regular registrations) <ul style="list-style-type: none"> ★ Registration Fee Includes: Technical Sessions, Conference Kit, Welcome Reception, Banquet, Lunches

Floor Plan



Exhibition Equipment and General Information

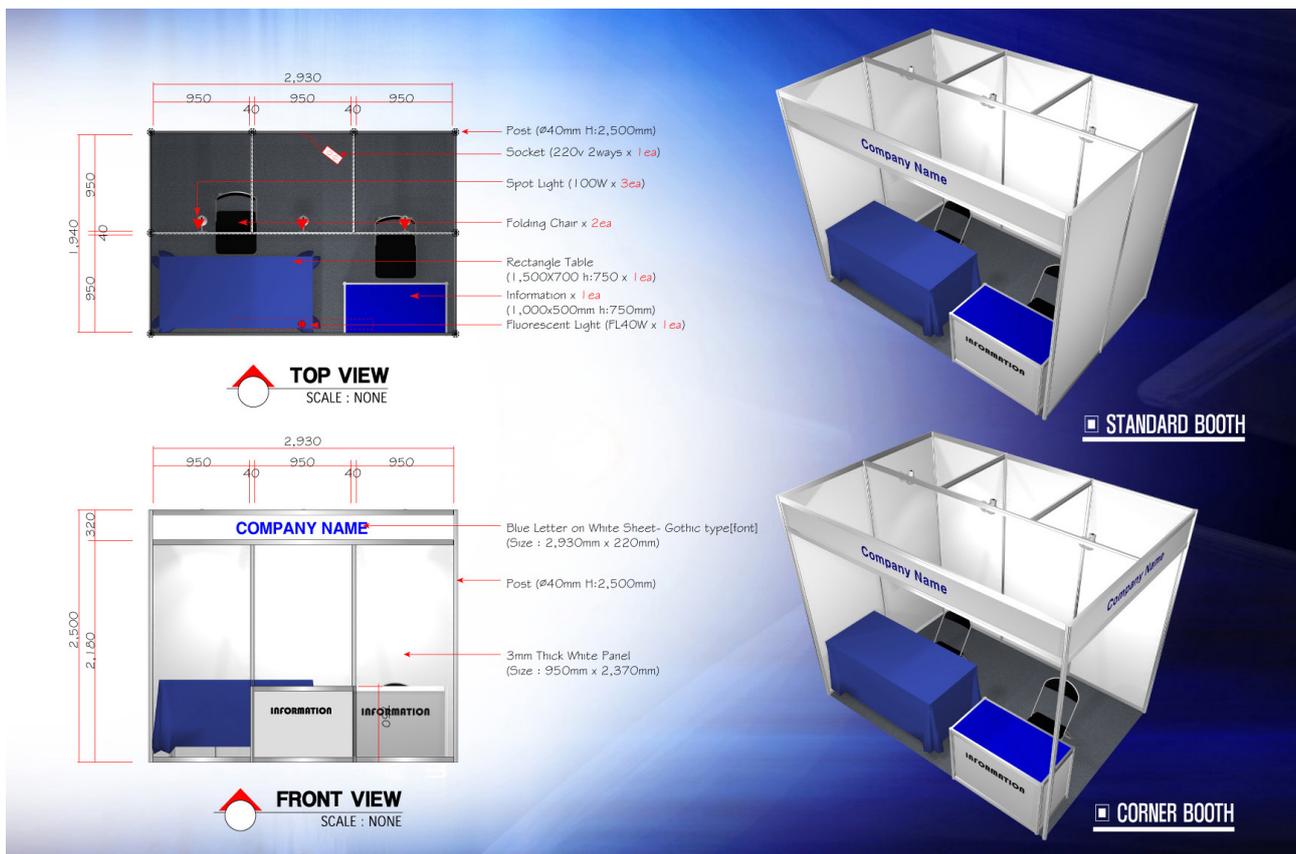
Standard Booth Equipment

- If the exhibitor requires design changes such as changing the color besides the basic standard booth specifications provided by organizers, exhibitor must request to the specified equipment manufacturers, and costs for additional services shall be paid by the exhibitor separately.
- The exhibitor shall be responsible for compensating any damages by painting, nailing, sticking with glue to attach exhibition materials to the standard booth panel.
- Exhibitor should apply extra electricity except the basic electricity (1kW) if it needs.

Standard Booth Package (1 booth = 6 sqm)

- Side and Rear Walls (white) / Wall to Wall Carpeting (3m width x 2m depth x 2.5m height)
- Fascia Board with Company Name (0.3m high, set at a height of 2.2m from the floor)
- 1 Information Desk / 1 Square Table / 2 Chairs
- 1kW Electricity / 3 Spotlights / 1 Fluorescent Light / Internet wi-fi Access

Standard Booth Design





Exhibition Application Form

A. Company Information

Name of Company			
Address			
Country		Name of President	
Person in Charge		Division in Charge	
Tel		Website	
E-mail			

B. Rental

Standard Booth (3m×2m×2.5m)	<input type="checkbox"/> USD 3,000
Participation Fee Includes	<ul style="list-style-type: none"> ① Costs and Charges for Exhibition Space, Standard Booth Package ② Directory Entry, Exhibitor Passes ③ 2 Free Registrations per Booth

• If you like to apply for additional furniture, electricity, other services (electricity, compressed air, etc.), please contact secretariat of HT-CMC 11.

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D. Booth Positioning

• Organizer shall allocate the space considering the floor space, the order of applications received, the type of the products and other reasonable standards.

By signing this form, I apply for the exhibition of HT-CMC 11 and agree to the HT-CMC 11 Exhibition terms and conditions.

Company Authorized Signature : _____ Date : _____

Secretariat of HT-CMC 11	Contact Person: Ms. Minjung Kim E-mail: secretary@ht-cmc11.org	Tel: +82-2-565-3571 Website: www.ht-cmc11.org
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